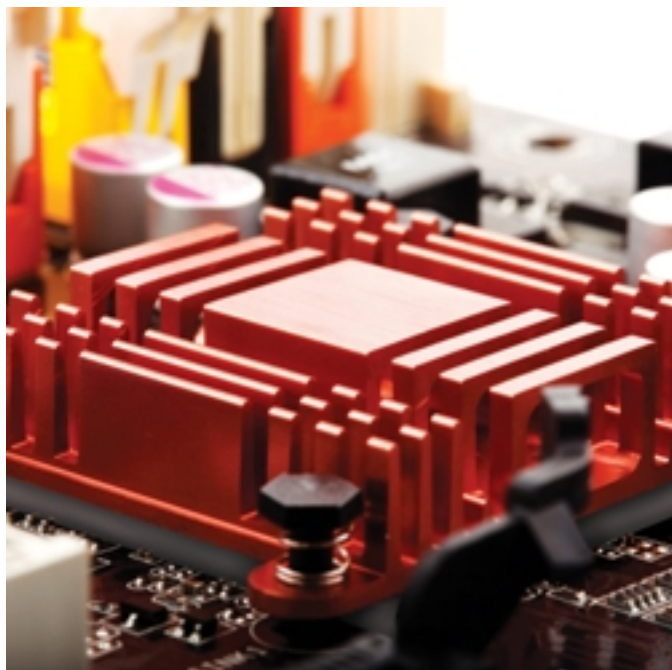


Thermal Gap Filler Material



The worldwide appetite for advanced technology is growing at a record pace. In order to stay ahead of this demand curve, electronics manufacturers are looking for new opportunities to integrate emerging technologies on the same board. Today, it is common practice to incorporate multi-band communications, GPS, video and high-speed processors within a very small device footprint.

To help remove performance-killing heat from these types of complex, multi-level printed circuit board designs, Fujipoly has developed Sarcon® GR-SL, an extremely low compression and high-performance thermal gap filler material. When placed on top of uneven components, this material quickly conforms to all gaps, peaks and air pockets making a level, large surface area contact point. The high degree of physical contact allows the heatsink to more efficiently remove unwanted heat.

As Fujipoly's softest gap filler pad, this unique formulation provides a thermal conductivity of 2.7 W/m°K with a thermal resistance between 0.94 and 1.69 °Cin²/W depending on sheet thickness. The V-0 tested Sarcon® GR-SL is available in 2.5 or 5.0mm thick sheets up to a maximum 200x300mm dimension and has an operating temperature of -40 to +150°C.

Source URL (retrieved on 01/27/2015 - 7:41pm):

<http://www.mdtmag.com/product-releases/2011/09/thermal-gap-filler-material>